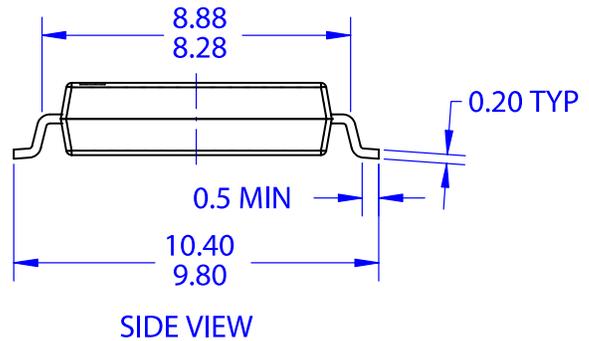
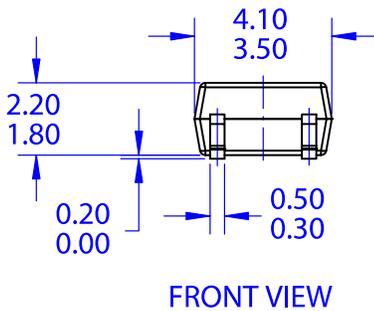
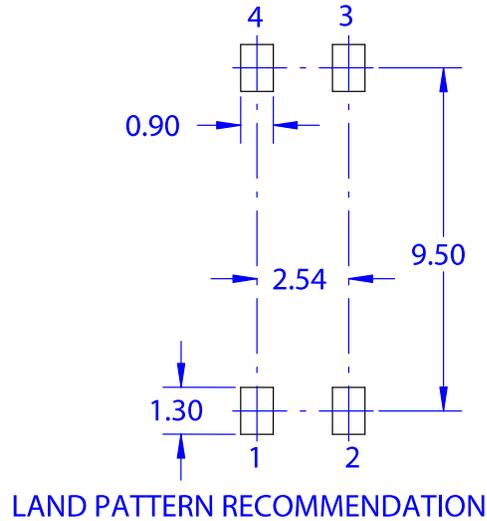
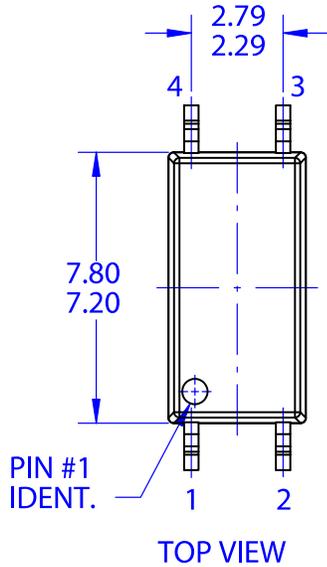


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

**SSOP4 / LSOP04**  
CASE 565BH  
ISSUE O

DATE 31 JAN 2017



**NOTES:**

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS

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<b>DESCRIPTION:</b>	<b>SSOP4 / LSOP04</b>	<b>PAGE 1 OF 1</b>

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